



PCN / EOL Notification

Product Change Notification Number: HC093601

Date*: September 9, 2009

Title: VIA Layer Change for T2526NxxxH and Transfer Wafer Fab Location from Heilbronn to Atmel Colorado Springs, CO.

Product Identification:

[See Attachment A](#)

Reason for Change:

☐ Design

☒ Manufacturing Location

☐ Processing

☐ Quality/Reliability

☐ Logistics

☒ Material

Change Description:

Changes to the VIA layer to improve bondability of the dies located close to the edge of the wafer – yield improvement. Process: BiCMOS. Wafer Fab: Transfer from Heilbronn to Atmel Colorado Springs, CO.

Identification Method to Distinguish Change:

The letter behind the part number changes from **N** to **S**.

The letter behind the frequency identifier is now **C**.

New Part Number: T2526**S**xxx**C**-DDW

Qualification Data:

☒ available

☐ will be available in WW__

☐ not applicable

Samples:

☒ available

☐ will be available in WW__

☐ not applicable

Quantifiable Impact on Quality & Reliability:

No impact on quality and reliability.

Estimated Availability Date: Available now

Last Time Buy Date: November 30, 2009

Last Ship Date: February 28, 2010

** All orders placed after the notification date are **non-cancellable** and **non-returnable (NCNR)**.*

Atmel Contact:

pcnadm@atmel.com

Atmel will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the Atmel Contact e-mail address listed above.

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Attachment A

Old Part Number	New Part Number
T2526N030H-DDW	T2526S030C-DDW
T2526N036H-DDW	T2526S036C-DDW
T2526N037H-DDW	T2526S037C-DDW
T2526N038H-DDW	T2526S038C-DDW
T2526N040H-DDW	T2526S040C-DDW
T2526N056H-DDW	T2526S056C-DDW
T2526N136H-DDW	T2526S136C-DDW
T2526N138H-DDW	T2526S138C-DDW
T2526N140H-DDW	T2526S140C-DDW
T2526N156H-DDW	T2526S156C-DDW
T2526N230H-DDW	T2526S230C-DDW
T2526N236H-DDW	T2526S236C-DDW
T2526N237H-DDW	T2526S237C-DDW
T2526N238H-DDW	T2526S238C-DDW
T2526N240H-DDW	T2526S240C-DDW
T2526N256H-DDW	T2526S256C-DDW
T2526N330H-DDW	T2526S330C-DDW
T2526N333H-DDW	T2526S333C-DDW
T2526N336H-DDW	T2526S336C-DDW
T2526N337H-DDW	T2526S337C-DDW
T2526N338H-DDW	T2526S338C-DDW
T2526N340H-DDW	T2526S340C-DDW
T2526N356H-DDW	T2526S356C-DDW
T2526N630H-DDW	T2526S630C-DDW
T2526N638H-DDW	T2526S638C-DDW
T2526N640H-DDW	T2526S640C-DDW
T2526N656H-DDW	T2526S656C-DDW
T2526N733H-DDW	T2526S733C-DDW
T2526N736H-DDW	T2526S736C-DDW
T2526N737H-DDW	T2526S737C-DDW
T2526N738H-DDW	T2526S738C-DDW
T2526N740H-DDW	T2526S740C-DDW
T2526N756H-DDW	T2526S756C-DDW